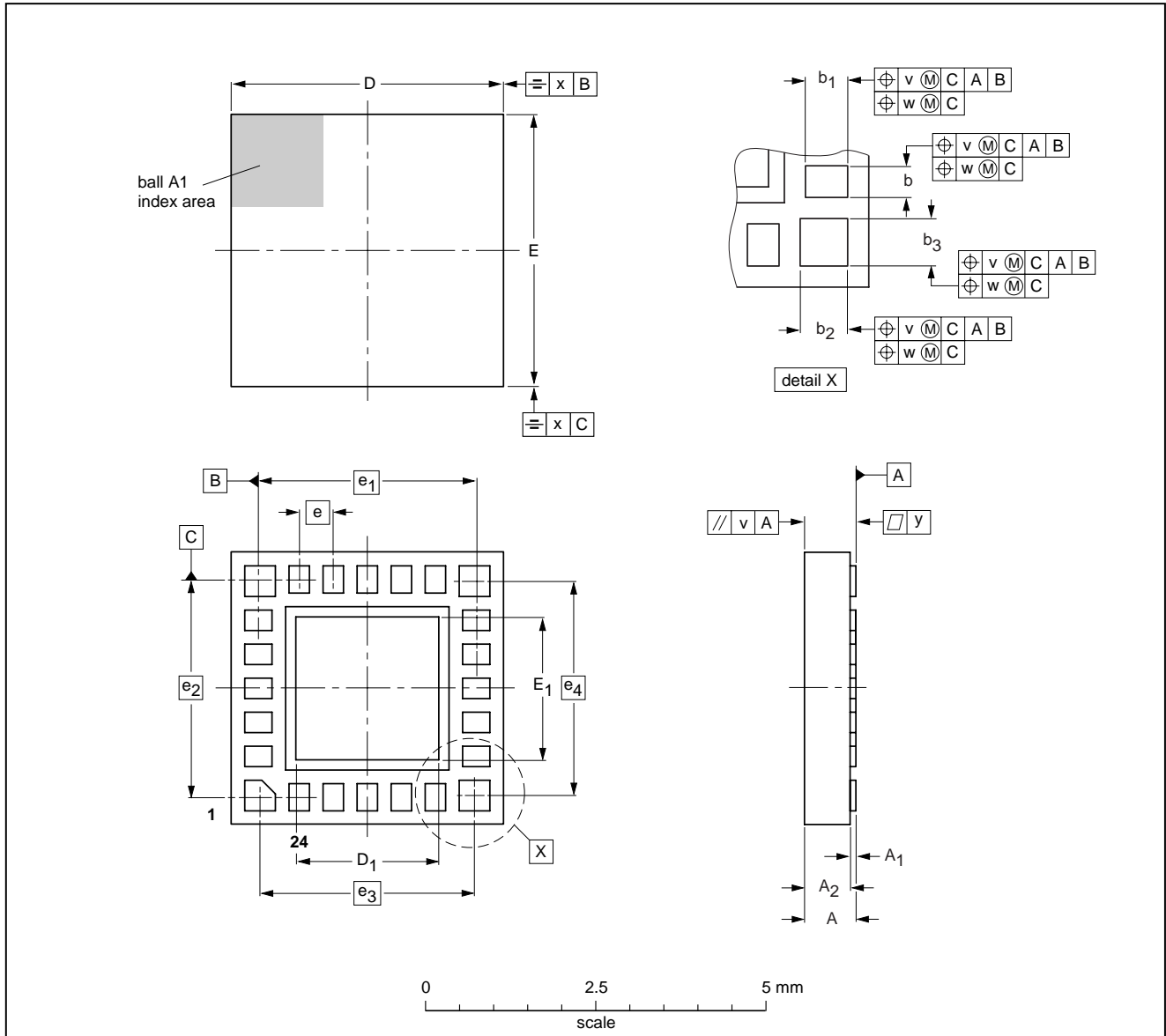


HBCC24: plastic thermal enhanced bottom chip carrier; 24 terminals; body 4 x 4 x 0.65 mm

SOT564-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	b <sub>1</sub>	b <sub>2</sub>	b <sub>3</sub>	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>	e <sub>4</sub>	v	w	x	y
mm	0.8	0.10 0.05	0.7 0.6	0.35 0.20	0.5 0.3	0.50 0.35	0.50 0.35	4.1 3.9	2.2 2.0	4.1 3.9	2.2 2.0	0.5	3.2	3.2	3.15	3.15	0.2	0.15	0.15	0.05

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT564-1		MO-217				00-08-28 03-03-12